SIEMENS

# Course Description

Xpedition

## Xpedition Advanced Packaging

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| Course Code | 252536-US |
| Software | Xpedition vx2.14 |
| User Level | All |
| PricingID | Contact Us |
| Live Online Duration | 6 hours for each day for 4 days |

The Xpedition Advanced Tech option enables 3D Advanced Packaging design in Xpedition layout. This includes IC packaging, MCM/Hybrid Design, and Mixed-signal SiP design. Xpedition Package Designer tool offers all of this capability native in the tool.

3D Wire bonding, Chip Stacking, and Substrate Cavities are supported in this flow and are covered in this class.

Hands-on lab exercises will reinforce lecture and discussion topics under the guidance of our industry expert instructors.

### PREREQUISITES

- Familiarity with the concepts of wire bonding, cavities, chip stacking
- Familiar with the use of Xpedition layout or Package designer tools in general

### PRIMARY COURSE TOPICS

#### You Will Learn How To

- Set up and implement chip stacking
- Create substrate cavities and place parts in cavities
- Create Keep out zones around cavities
- Create library needs for wire bonding
- Set up and implement 3D wire bonding including a chip to chip and RF wire bonding
- Set up and run 2D and 3D DRC for wire bonding
- Learn basic and advanced features used with wire bonding
- Learn how to troubleshoot problems associated with wire bonding

#### Hands-On Labs

Throughout this course, hands-on lab exercises provide you with practical experience using Xpedition Advanced Packaging capabilities. Hands-on lab topics include:

- Creation of die pin pad stacks
- Creation of Bond pad stacks
- Creation of wire bondable chip component in Central library
- Adding a substrate cavity
- Placing parts in cavities and implementing wire bonding
- Explore many methods of placing wire bonds
- Run 2D and 3D DRC on wire bonding